Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**B**

**E**

**.024”**

**.024”**

**Top Material: Al**

**Backside Material: NiAuAg**

**Bond Pad Size: .004” X .004”**

**Backside Potential: COLLECTOR**

**Mask Ref: DB078E**

**APPROVED BY: DK DIE SIZE .024” X .024” DATE: 9/23/21**

**MFG: FAIRCHILD THICKNESS .007” P/N: BC640TA**

**DG 10.1.2**

#### Rev B, 7/1